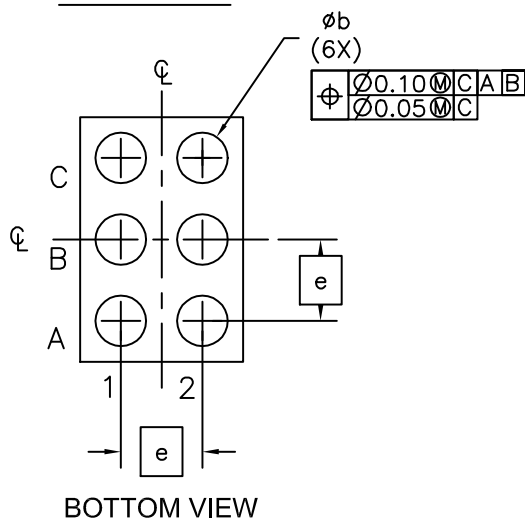
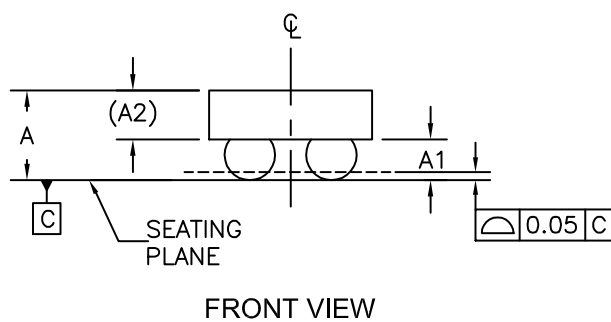
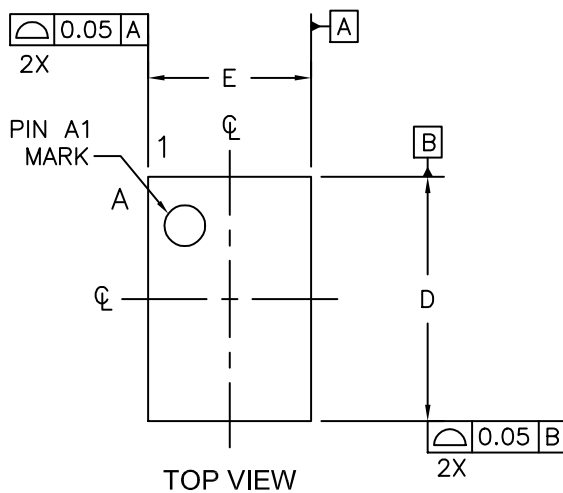


**WLCSP6 1.5x1x0.6**  
CASE 567PW  
ISSUE A

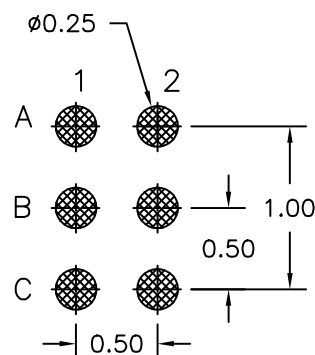
DATE 04 AUG 2021



NOTES: UNLESS OTHERWISE SPECIFIED

- A) ALL DIMENSIONS ARE IN MILLIMETERS.  
B) NO JEDEC REGISTRATION REFERENCE  
AS OF OCTOBER 2005.  
C) DRAWING CONFORMS TO ASME  
Y14.5M-2009

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	-	-	0.60
A1	0.22	0.25	0.28
A2	0.30 REF		
b	0.24	0.31	0.39
D	1.45	1.50	1.55
E	0.95	1.00	1.05
e	0.50 BSC		



## LAND PATTERN RECOMMENDATION

\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>WLCSP6 1.5x1x0.6</b>	<b>PAGE 1 OF 1</b>

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